



Material and Finish

Insulator: HT thermoplastic, UL94V-0 rated, black or white color, Reflow Process Compatible-
 Recommended Soldering Temperature: 230°C for 30 seconds, 260°C max.
 Shield: brass, 0.30mm thick
 Shield Finish: 120u" nickel plated over 50u" copper underplate
 Contact Material: phosphor bronze
 Contact Plating Options:
 Standard: gold flash on contact area, 120u" min. tin on soldertails, all over 50u" min. nickel underplate
 -30 Option: 30u" gold on contact area, 120u" min. tin on soldertails, all over 50u" min. nickel underplate

Specifications:

Contact Current Rating: 1A max.
 Contact Resistance: 30 milliohms max.
 Insulation Resistance: 1000 Megohms min.
 Dielectric Withstanding Voltage: 500V AC
 Insertion Force: 3.57kg max.
 Extraction Force: 1.02kg min.
 Operating Temperature: -25°C to +80°C
 Durability: 1500 mating cycles min.

Part Number	Contact Area Plating Finish	Insulator Color	Packaging
KUSBLX-SMT-AS1N-W	Gold Flash (standard)	White	Bulk (trays, standard)
KUSBLX-SMT-AS1NW30	30u" Gold (30 option)	White	Bulk (trays, standard)
KUSBLX-SMT-AS1N-B	Gold Flash (standard)	Black	Bulk (trays, standard)
KUSBLX-SMT-AS1NB30	30u" Gold (30 option)	Black	Bulk (trays, standard)
KUSBLXSMTAS1NWTR	Gold Flash (standard)	White	Tape & Reel (TR option)
KUSBLXSMTAS1NW30TR	30u" Gold (30 option)	White	Tape & Reel (TR option)
KUSBLXSMTAS1NBTR	Gold Flash (standard)	Black	Tape & Reel (TR option)
KUSBLXSMTAS1NB30TR	30u" Gold (30 option)	Black	Tape & Reel (TR option)



Tolerances
X.X ± 0.25
X.XX ± 0.15
Unless Stated Otherwise

REV.	DATE	DESCRIPTION	REV. BY	CHK. BY	DRAWN BY	DATE
A1	10/4/05	New Drawing	R. Aguirre	H. MA	R. Aguirre	8/01/05

KUSBLX-SMT-AS1N-x
 xxx = color and plating options

Surface Mount A-Type USB Socket, RoHS Compliant
 Low Profile Mount, w/ Tape & Reel Option

